## IN THE CLAIMS:

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- 1. (Currently Amended) A positive photosensitive composition comprising:
- (A) an alkali soluble organic high molecular substance having a phenolic hydroxyl group;
- (B) a photo-thermal conversion material that absorbs infrared rays from an image exposure light source and converts it to heat;
- (C) at least one resin selected from the group consisting of: (1) vinylpyrrolidone/vinyl acetate copolymer, (2) vinylpyrrolidone/dimethyl- aminoethyl methacrylate copolymer, (3) vinylpyrrolidone/vinyl caprolactam/ dimethylaminoethyl methacrylate copolymer, (4) polyvinyl acetate, (5) polyvinyl butyral, (6) polyvinyl formal, (7) styrene/maleic acid copolymer, (8) terpene phenol resin, (9) alkylphenol resin, (10) melamine/formaldehyde resin, and (11) ketone resin; and
- (D) a dissolution inhibitor, said alkali soluble organic high molecular substance being in a range from 80 to 95 wt. % of the total solid amount of components (A), (B), (C) and (D), said photo-thermal conversion material being in a range from 0.1 to 10 wt. % of the total solid amount of components (A), (B), (C) and (D), said dissolution inhibitor being in a range from 0.5 to 8 wt. % of the total solid amount of components (A), (B), (C) and (D).
- 2. (Original) The positive photosensitive composition according to claim 1, wherein the dissolution inhibitor (D) is a compound represented by the following chemical formula (1).

\_\_\_\_\_3. (Previously Presented) The positive photosensitive composition according to claim 1, wherein the photo-thermal conversion material (B) is a compound represented by the following formula (2).

$$\begin{bmatrix} R_1 & H_3C & CH_3 & CI & H_3C & CH_3 & R^4 \\ R^2 & CH & CH & CH & CH & CH & R^5 \end{bmatrix} \xrightarrow{R^4} \cdots (2)$$

wherein each of "R1" to "R6" independently represents a hydrogen atom, an alkyl group having 1 to 3 carbon atoms, or an alkoxyl group having 1 to 3 carbon atoms, and "X" represents a halogen atom, ClO<sub>4</sub>, BF<sub>4</sub>, p-CH<sub>3</sub>C<sub>6</sub>H<sub>4</sub>SO<sub>3</sub>, or PF<sub>6</sub>.

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4. (Previously Presented) The positive photosensitive composition according to claim 1, wherein the photo-thermal conversion material (B) is a compound represented by the

following formula (3).

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$$\begin{bmatrix}
R^7 \\
C = C - C + C = C
\end{bmatrix}$$

$$R^9 \\
R^{10}$$

$$R^{10}$$

wherein each of " $R^7$ " ~" $R^{10}$ " independently represents a hydrogen atom, a methoxyl group,  $N(CH_3)_2, \text{ or } N(C_2H_5)_2, \text{ and "Y" represents } C_4H_9-B(C_6H_5)_3, \text{ p-CH}_3C_6H_4SO_3, \text{ or } CF_3SO_3.$ 

5. (Currently Amended) A photofabrication method comprising:
providing a positive photosensitive composition, said photosensitive composition
including:

(A) an alkali soluble organic high molecular substance having a phenolic hydroxyl group;

(B) a photo-thermal conversion material that absorbs infrared rays from an image exposure light source and converts it to heat;

(C) at least one resin selected from the group consisting of: (1)

vinylpyrrolidone/vinyl acetate copolymer, (2) vinylpyrrolidone/dimethyl- aminoethyl

methacrylate copolymer, (3) vinylpyrrolidone/vinyl caprolactam/ dimethylaminoethyl

methacrylate copolymer, (4) polyvinyl acetate, (5) polyvinyl butyral, (6) polyvinyl formal,

(7) styrene/maleic acid copolymer, (8) terpene phenol resin, (9) alkylphenol resin, (10) melamine/formaldehyde resin, and (11) ketone resin; and

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(D) a dissolution inhibitor, said alkali soluble organic high molecular substance being in a range from 80 to 95 wt. % of the total solid amount of components (A), (B), (C) and (D), said photo-thermal conversion material being in a range from 0.1 to 10 wt. % of the total solid amount of components (A), (B), (C) and (D), said dissolution inhibitor being in a range from 0.5 to 8 wt. % of the total solid amount of components (A), (B), (C) and (D);

applying the positive photosensitive composition to a subject to be coated; exposing the positive photosensitive composition as defined in claim 1 to a laser beam having a wavelength of from 700 to 1,100 nm. to form a positive image without burning after the applying step.

- 6. (Previously Presented) The photo fabrication method according to claim 5, further comprising the step of applying said photosensitive composition to the production of a printing plate, an electronic component [[and]] or a precision equipment component.
- 7. (Currently Amended) A plate-making method comprising:

  providing a positive photosensitive composition, the positive photosensitive
  composition including:

(A) an alkali soluble organic high molecular substance having a phenolic hydroxyl group;

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(B) a photo-thermal conversion material that absorbs infrared rays from an image exposure light source and converts it to heat;

(C) at least one resin selected from the group consisting of: (1)

vinylpyrrolidone/vinyl acetate copolymer, (2) vinylpyrrolidone/dimethyl- aminoethyl

methacrylate copolymer, (3) vinylpyrrolidone/vinyl caprolactam/ dimethylaminoethyl

methacrylate copolymer, (4) polyvinyl acetate, (5) polyvinyl butyral, (6) polyvinyl formal,

(7) styrene/maleic acid copolymer, (8) terpene phenol resin, (9) alkylphenol resin, (10)

melamine/formaldehyde resin, and (11) ketone resin; and

(D) a dissolution inhibitor, said alkali soluble organic high molecular substance being in a range from 80 to 95 wt. % of the total solid amount of components (A), (B), (C) and (D), said photo-thermal conversion material being in a range from 0.1 to 10 wt. % of the total solid amount of components (A), (B), (C) and (D), said dissolution inhibitor being in a range from 0.5 to 8 wt. % of the total solid amount of components (A), (B), (C) and (D);

applying the positive photosensitive composition to a subject to be coated; exposing the positive photosensitive composition as defined in claim 1 to a laser beam having a wavelength of from 700 to 1,100 nm. to form a positive image without burning after the applying step.

\_\_\_\_\_\_8. (Previously Presented) The positive photosensitive composition according to claim 2, wherein the photo-thermal conversion material (B) is a compound represented by the following formula (2).

wherein each of "R<sup>1</sup>" to "R<sup>6</sup>" independently represents a hydrogen atom, an alkyl group having 1 to 3 carbon atoms, or an alkoxyl group having 1 to 3 carbon atoms, and "X" represents a halogen atom, ClO<sub>4</sub>, BF<sub>4</sub>, p-CH<sub>3</sub>C<sub>6</sub>H<sub>4</sub>SO<sub>3</sub>, or PF<sub>6</sub>.

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9. (Previously Presented) The positive photosensitive composition according to claim 2, wherein the photo-thermal conversion material (B) is a compound represented by the following formula (3).

wherein each of " $R^7$ " ~" $R^{10}$ " independently represents a hydrogen atom, a methoxyl group,  $N(CH_3)_2$ , or  $N(C_2H_5)_2$ , and "Y" represents  $C_4H_9$ - $B(C_6H_5)_3$ , p- $CH_3C_6H_4SO_3$ , or  $CF_3SO_3$ .

10. (Currently Amended) A photofabrication method comprising:

applying the positive photosensitve composition as defined in claim 2 to a subject to be coated;

exposing the positive photosensitive composition as defined in claim 2 to a laser beam having a wavelength of from 700 to 1,100 nm. to form a positive image without burning after the applying step.

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- 11. (Previously Presented) The photofabrication method according to claim 10, further comprising the step of applying said positive photosensitive composition to the production of a printing plate, an electronic component or a precision equipment component.
- 12. (Currently Amended) A plate-making method comprising:

  applying the positive photosensitive composition as defined in claim 2 to a subject to be coated;

exposing the positive photosensitive composition as defined in claim 2 to a laser beam having a wavelength of from 700 to 1,100 nm. to form a positive image without burning after the applying step.